

# 2SC5346

## Silicon NPN epitaxial planar type

For low-frequency high breakdown voltage amplification  
Complementary to 2SA1982

### ■ Features

- Satisfactory linearity of forward current transfer ratio  $h_{FE}$
- High collector to emitter voltage  $V_{CEO}$
- Small collector output capacitance  $C_{ob}$

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector to base voltage	$V_{CBO}$	150	V
Collector to emitter voltage	$V_{CEO}$	150	V
Emitter to base voltage	$V_{EBO}$	5	V
Peak collector current	$I_{CP}$	100	mA
Collector current	$I_C$	50	mA
Collector power dissipation *	$P_C$	1.0	W
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

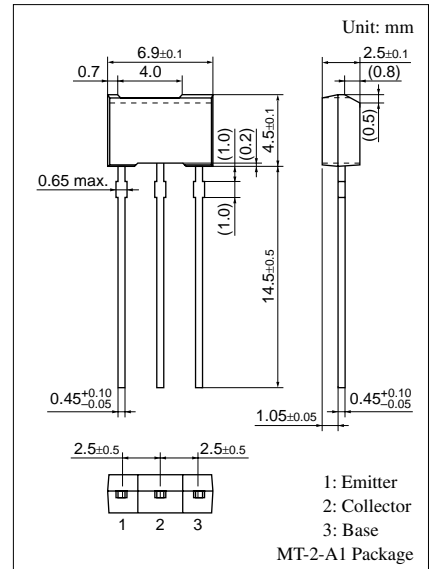
Note) \*: Printed circuit board: Copper foil area of 1 cm<sup>2</sup> or more, and the board thickness of 1.7 mm for the collector portion

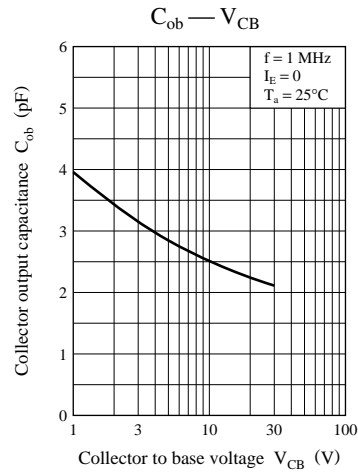
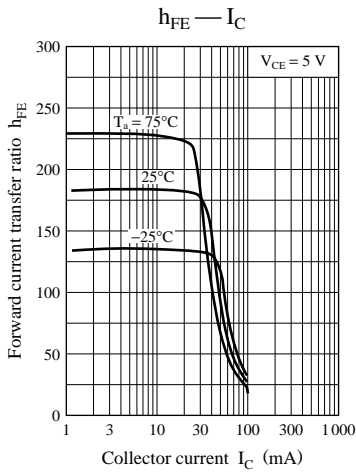
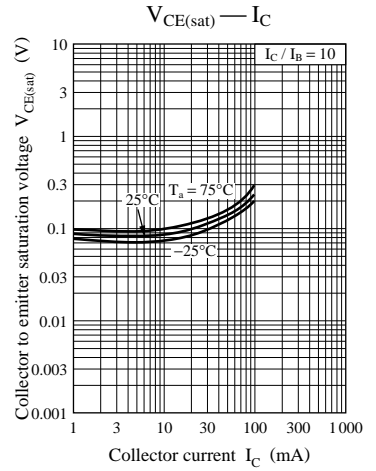
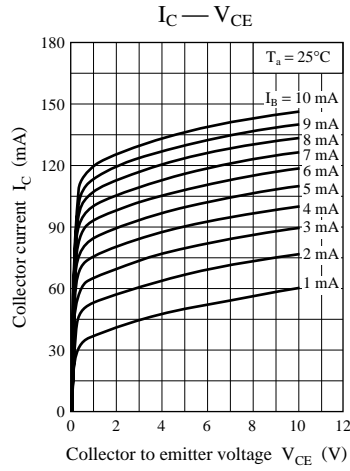
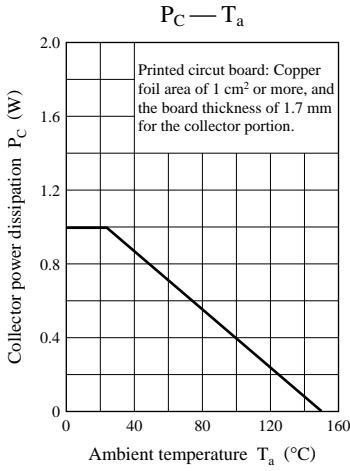
### ■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector cutoff current	$I_{CBO}$	$V_{CB} = 100\text{ V}, I_E = 0$			1	$\mu\text{A}$
Collector to emitter voltage	$V_{CEO}$	$I_C = 0.1\text{ mA}, I_B = 0$	150			V
Emitter to base voltage	$V_{EBO}$	$I_E = 10\ \mu\text{A}, I_C = 0$	5			V
Forward current transfer ratio *	$h_{FE}$	$V_{CE} = 5\text{ V}, I_C = 10\text{ mA}$	130		330	
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = 30\text{ mA}, I_B = 3\text{ mA}$			1	V
Noise voltage	NV	$V_{CE} = 10\text{ V}, I_C = 1\text{ mA}, G_V = 80\text{ dB}$ $R_g = 100\text{ k}\Omega, \text{Function} = \text{FLAT}$		150	300	mV
Transition frequency	$f_T$	$V_{CB} = 10\text{ V}, I_E = -10\text{ mA}, f = 200\text{ MHz}$		160		MHz
Collector output capacitance	$C_{ob}$	$V_{CB} = 10\text{ V}, I_E = 0, f = 1\text{ MHz}$			5	pF

Note) \*:  $h_{FE}$  Rank classification

Rank	R	S
$h_{FE}$	130 to 220	185 to 330





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